

Surface-Mount Devices | 1206 Size

SRF1206 Series

PTC Resettable Fuses

Features

- Resettable over current and over temperature protection
- Small size of 1206
- Fast time-to-trip
- Small footprint
- RoHS complaint
- Low resistance







Applications

- Computer
- Portable electronics
- Multimedia
- Game machines
- Telephony and broadband
- Mobile phones
- Battery
- Industrial controls



Electrical Characteristics

	l _Η	I_{T}	V_{max}	I_{max}	Time to Trip		Pd_{typ}	R_{min}	$R1_{\text{max}}$
Part Number	(A)	(A)	(V)	(A)	(A)	(Sec.)	(W)	(Ω)	(Ω)
SRF1206P050/24	0.50	1.00	24	40	8.0	0.10	0.6	0.15	0.80

I_H = Hold current: maximum current at which the device will not trip at 25 °C still air reflow soldering of 260 ℃ for 20 sec.

R1_{max} = Maximum resistance of device at 25 °C measured one hour after reflow soldering

Value specified is determined by using the PWB with 0.030" *1.5oz copper traces. Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

Thermal Derating Chart Hold Current (A)

Ambient Operating Temperature Part Number **-40°**C -20°C 0°C **25**°C **40**°C **50°**C **70°C 85**°C **60**°C SRF1206P050/24 0.71 0.64 0.57 0.50 0.42 0.39 0.31 0.35 0.25

I_T = Trip current: minimum current at which the device will always trip at 25 °C still air reflow soldering of 260 °C for 20 sec.

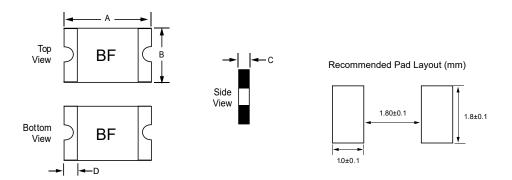
V_{max} = Maximum continuous voltage device can withstand without damage at rated current

I_{max} = Maximum fault current device can withstand without damage at rated voltage.

 T_{trip} = Maximum time to trip(s) at assigned current reflow soldering of 260 $^\circ$ for 20 sec. P_{dyp} = Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

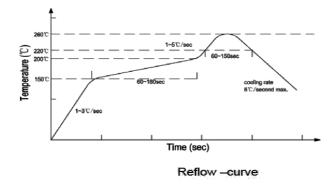
R_{min} = Minimum resistance of device in initial (un-soldered) state.

Dimensions



Part Number	Α			3	С		D
	Min	Max	Min	Max	Min	Max	Min
SRF1206P050/24	3.00	3.60	1.50	1.90	0.40	1.00	0.10

Solder Reflow Recommendation



Recommended reflow methods:IR,hot air oven ,nitrogen oven

Devices can be cleaned using standard industry methods and solvents.

NOTE:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame

Packaging Options

Part Number	Quantity
SRF1206P050/24	3,500pcs

Reel packaging per EIA-481-1 standard

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